# ■ MN103E010HRA, MN103E040HYB

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Туре	MN103E010HRA	MN103E040HYB								
Instruction Cache	16 K-byte (4-way, set-associative)									
Data Cashe	16 K-byte (4-	way, set-associative)								
SRAM Used by Both	16 K-byte									
Instructions and Data										
Package	BGA292-P-2727 *Lead-free	FLGA424-C-1717 *Lead-free								
Minimum Instruction Execution Time	7.5 ns (at 1.8 V tol-	erance = ± 5%, 133 MHz)								
Interrupts	• XIRQ × 8 • NMI • Timer × 14 • DMAC × 4 • WD • Realtime clock • Asynchronous bus error	T • A/D • SIO × 6 • $I^2C \times 2$ • IrDA • Softmodem								
Timer Counter	8-bit timer × 4 (all down counters)  Cascade connection possible (usable as a 16/24  Timer output possible (Duty = 1:1)  Internal clock source or external clock source s  Selectable as a serial interface clock									
	16-bit timer × 7 (down counters)  Cascade connection possible (usable as a 32-bit Timer output possible (Duty = 1:1)  Internal clock source or external clock source s  Partially selectable as a serial interface clock									
	16-bit timer × 1 (up counter)  Internal clock source or external clock source selectable  Input capture function (rising edge, falling edges, or both selectable)  PWM generating function (compare/capture register × 2 contained)  Watchdog timer × 1									
DMA Contoroller	Number of channels: 4									
DIMA CONTOINE	Transfer unit: 1/2/4/16 byte									
	Maximum number of bytes transferred: 1Mbyte									
	Start factor: External request, interrupt, software									
	Transfer mode: 2-bus cycle transfer									
	Transfer mode: Batch transfer, intermittent transfer									
	Addressing mode: Source/destination each fixed, increment/decrement sp	equification possible								
	Increment/decrement automatically executed according	-								
Serial Interface	UART/synchronous (co-used) × 2-ch.	-								
Jonai mioriado	UART (with CTS control) × 1-ch.									
I/O Pins I/O	34 • Common use : 33									
FPU (floating point unit)	Data types complying with the IEEE754 standard support of the standard su	pported								
• (	• Round to the nearest mode complying with the IEEE754 standard supported									
	• 32 single-precision floating point operation registers	* *								
	These can also be referenced as 16 double-precision • Floating point operation exceptions (5 types) and floatEEE754 standard supported	floating point operation registers (FD0-FD30) ating point unload instruction exceptions complying with the								
Memory Management Function	32-entry full-associative TLB loaded (instructions/data Address conversion by paging (page size: 1 K-byte. 4	- ·								
On-chip Bus Controller	Concurrent access from three types of master devices t	to four types of slave devices possible								

### MN103E010HRA, MN103E040HYB □

System Bus Interface	External memory space allocation to 8 banks possible  The external interface can use the built-in memory, RAM, ROM, SDRAM interfaces
Memory Bus Interface	SDRAM directly connected interface contained
Soft Modem Interface	Interface with an external AFE (analog front end)
Con modern micriaes	Output data parallel-serial conversion, input data serial-parallel conversion
	• Send/receive FIFO contained (16-bit width, 16 steps)
	• NCU control via the parallel IO port
Real-time Clock	Clock/calendar function
	• Interrupt: periodic, alarm, update ended
	BCD/binary accommodated
	• Leap year automatic correcting function
	• 24-hout/12-hour selectable
	Daylight saving time mode accommodated
A/D Converter	• 10-bit charge re-distribution mode (error: ±4LSB)
	• Number of channels: 8-channel
IrDA Interface	• IrDA 1.0 SIR (-115.2 Kb/s, half-duplex)
	• IrDA 1.1 MIR (0.576, 1.152 Mb/s, half-duplex)
	• IrDA 1.1 FIR (4.0 Mbp/s, half-duplex)
	• UART (-1.5 Mbp/s, full-duplex)
	• 48 MHz clock input (baud rate generating function contained)
I <sup>2</sup> C Interface	2 ports
	Master-slave interface (multi-master supported)
	3.3 V interface (open drain output)

#### Electrical Characteristics

#### Supply current

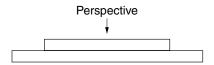
Parameter	Symbol	Condition		Unit		
r ai ailletei	Symbol	Gondinon		typ	max	June
Operating supply current	IDD18A	VDD18 = 1.8 V ; VDD33, PVDD, AVDD, RVDD = 3.3 V			460	4
		fOSC = 33.33  MHz  (core  133  MHz)  ;  FRQS[1:0] = 0.0  ; Output open	-	_	400	mA
Supply ourrant at stanning	I	VDD18 = 1.89 V ; VDD33, PVDD, AVDD, RVDD = 3.465 V			50	4
Supply current at stopping	IDD18D	$fOSC = Stop$ ; $FRQS[1:0] = 0.0$ ; Output open; $Tj = 70^{\circ}C$	_	_	30	mA
				/T-	2000	- · 700C)

 $(Ta = -20^{\circ}C \text{ to } +70^{\circ}C)$ 

#### A/D conversion performance

Parameter	Symbol	Condition		Unit		
		Condition	min	typ	max	Oint
Resolution			-	-	10	Bit
A/D conversion relative error		VREFH = 3.3 V	-	-	±4	LSB
A/D conversion differential non-linear error	Dconversion differential non-linear error Conversion reference clock = 4.166 MHz			-	±4	LSB
A/D conversion time			2.6	-	-	μs

 $(Ta = -20^{\circ}C \text{ to } +70^{\circ}C, \text{ AVDD} = 3.3 \text{ V} \pm 0.165 \text{ V}, \text{ AVSS} = 0 \text{ V})$ 



		XSWE1	XSCS6	veces	XSCS1	SD29	SD27	VDD18	SD21	SD19	SD14	VDD18	SD6	SD1	CI V 40	PIO1[3]	DIOITI	DIO1101			21
N	D	ASWEI	ASCSO	XSCS2	ASCS1	SD29	SD27	VDDI8	SD21	3019	SD14	VDD18	300	SDI	CLN48	PIOI[3]	PIOI[I]	PIOI[0]	N	D	
		XSWE3	SD31	XSCS7	SD30	XSAS	SD23	SD22	SD17	SD16	SD9	SD8	SD3	SD4	PIO5[1]	PIO5[2]	PIO1[4]	PIO1[2]			20
RCLKI	XSCS3	XSWE0	XSWE2	XSCS0	XSCS4	SD28	SD25	SD24	SD18	VDD33	SD15	SD11	SD10	VDD33	PIO0[7]	PIO5[0]	AN1	AN3	AN7	VREFH	19
RCLKO	PIO2[0]	PWROK	ND	ND	ND	SD26	SD20	SD13	SD12	SD7	SD2	SD0	SD5	PIO0[1]	ND	ND	ND	AN5	PIO0[5]	AVSS	18
RVDD	PIO2[4]	PIO2[2]	ND	ND	ND	ND	AN6	AN0	AN2	17											
TCPOUT	PIO2[3]	XSDK	ND	ND	ND	ND	PIO0[3]	XIRQ7	AN4	16											
PVDD	SSZ0	XSBG	VDD33	ND	ND	ND	XIRQ4	SBT2	PIO0[4]	AVDD	15										
PVSS	SA4	SA2	XSCS5	ND	ND	ND	SBO0	XIRQ5	XNMI	XIRQ2	14										
osci	SA10	SA5	VDD33	ND	ND	ND	ND	vss	vss	vss	vss	VSS	ND	ND	ND	ND	SBO1	XIRQ0	PIO0[6]	PIO0[2]	13
osco	SA17	SA11	SA0	ND	ND	ND	ND	vss	VSS	VSS	vss	VSS	ND	ND	ND	ND	VDD33	XRESET	PIO0[0]	XIRQ6	12
SYSCLK	SA18	SA12	XSRE	ND	ND	ND	ND	vss	vss	vss	vss	vss	ND	ND	ND	ND	TRCST	VDD33	XIRQ3	VDD18	11
PIO2[1]	SRXW	SSZ1	VDD33	ND	ND	ND	ND	vss	vss	vss	vss	vss	ND	ND	ND	ND	SBI1	SBI2	SBO2	XIRQ1	10
XSBR	SA1	SA3	SA14	ND	ND	ND	ND	vss	VSS	VSS	vss	VSS	ND	ND	ND	ND	PIO3[2]	PIO3[3]	XRSTOUT	VDD18	09
VDD18	SA6	SA7	SA8	ND	ND	ND	PIO3[0]	PIO3[1]	SBT0	SBT1	08										
SA9	SA13	SA15	SA22	ND	ND	ND	TRST MOD	PIO4[0]	PIO4[2]	SBI0	07										
SA16	SA19	SA21	ND	ND	ND	ND	PIO4[1]	PIO3[4]	TCK	06											
VDD18	SA23	VDD33	ND	ND	ND	ND	TRCD1	PIO4[3]	TDI	05											
SA27	SA26	SA24	ND	ND	ND	VDD33	VDD18	VDD33	VDD33	VDD33	VDD33	VDD18	TRCD2	TRCD7	ND	ND	ND	TRCD5	TMS	TDO	04
SA29	SA31	SA25	SA20	SA28	MA4	MA1	MA7	MA13	MA11	MA12	XMBE0	MD9	MD4	MD12	MD1	MD15	TRCD4	TRCD0	EXTRG	TRCCLK	03
N	D.	SA30	MA3	MA5	MA0	MA8	MA14	XMCS1	SDCKE	XMWE	XMCAS	MD6	MD10	MD11	MD2	MD14	TRCD3	TRCD6	N	D	02
INI	<i>υ</i>	NP	MA2	MA6	MA10	MA9	XMCS0	XMRAS	SDCLK	XMBE1	MDK	MD7	MD8	MD5	SDCKI	MD3	MD13	MD0	IN.		01

A B C D E F G H J K L M N P R T U V W Y AA

FLGA424-C-1717 \*Lead-free

<sup>\*</sup> ND has an electrode (pin) but N.C. is not guaranteed. Please design so as not to cause short circuit with other wiring on the user board.

<sup>\*</sup> The NDs on the four corners are the lands intended for reinforcement. You are required to connect them to the PCB.

<sup>\*</sup> NP (No pin.) has no electrode.

#### Pin Assignment(Continue) Perspective TRST XRST OUT TRCD6 TRCD1 TDO PIO4[2] PIO3[2] SBI0 SBO1 SBT1 SBT2 XIRQ1 XIRQ4 XIRQ5 PIO0[0] PIO0[4] AVDD AN4 AVSS VREFH 20 MOD TRCD3 EXTRG TCK PIO4[0] PIO3[0] PIO3[3] SBO0 SBI1 XIRQ0 XIRQ2 XNMI XIRQ7 PIO0[2] PIO0[6] PIO1[2] PIO5[0] 19 TRCD7 TRCD4 TRCD0 TDI TMS PIO4[1] PIO3[1] PIO3[4] SBT0 SBO2 XRESET XIRQ3 XIRQ6 PIO0[1] PIO0[5] AN3 AN0 PIO1[1] PIO5[2] 18 MD0TRCD2 TRCD5 VSS VSS PIO4[3] VDD18 VDD33 VSS VDD18 VDD33 VSS PIO0[3] VSS PIO0[7] AN5 PIO1[0] PIO1[3] PIO5[1] CLK48 17 TRC CLK MD13 TRCST VSS VSS PIO1[4] SD3 ${\rm SD}0$ 16 MD3 MD14 MD15 VSS SD2 SD1 SD6 SD4 15 VD33 VDD33 MD2 MD1 SD5 SD9 SD7 sdcki 14 VD18 VSS VSS VSS VSS VSS VSS MD11 MD12 VSS SD10 MD5 SD8 SD12 13 VDD33 VSS VSS VSS VSS VSS VSS VDD18 SD11 MD8 MD10 MD4 SD15 SD13 12 MD7 VSS VSS VSS VSS VSS VSS VSS VDD33 SD14 SD17 SD16 MD6 MD9 11 MDK XMCAS XMBE0 VSS VSS VSS VSS VSS VSS VSS SD23 SD18 SD19 10 XMBEI XMWE MA12 VSS VSS VSS VDD18 SD21 SD20 SD22 09 SDCLK SDCKE VDD18 VSS VSS VSS VSS VSS VSS SD25 MA11 SD24 SD26 08 XMRAS XMCE1 MA13 VDD33 VDD33 SD29 SD27 07 XMCS0 MA14 MA7 VDD33 XSCS2 XSAS SD30 SD31 06 MA9 MA8 MA1 VSS VSS XSCS3 XSCS0 XSCS1 05 VDD18 VDD33 VDD18 VDD33 MA10 MA0 MA4 VSS VSS SA22 VSS VDD33 SA0 XSBR XSRE VSS VSS XSCS6 XSCS4 XSCS5 04XSBG PIO2[4] PIO2[3] PIO2[0] XSWE3 XSCS7 RCLKI MA6 MA5 SA31 **SA26** SA23 **SA19** SA16 SA13 SA9 SA10 SA1 VSS XSWE0 03 PIO2[2] PIO2[1] PWROK XSWE2 XSWE1 RCLKO MA2 MA3 SA28 SA25 SA21 **SA18** SA15 SA12 SA8 SA<sub>6</sub> SA2 SSZ0 SRXW 02 OUT

BGA292-P-2727 \*Lead-free

SA4

L

SA5

K

SSZ1

N

SA3

M

XSDK

P

CLK

R

OSCO

T

OSCI

U

PVSS

V

PVDD

W

RVDD

Y

01

#### **Support Tool**

**SA30** 

Α

SA29

В

SA27

C

SA24

D

SA20

E

SA17

F

SA14

G

SA11

Η

PARTNER-J (KMC product)

SA7

_	• •	
	ROM Emulator	PARTNER-ETII (KMC product)
	On-board Development Tools	PX-ODB103E-J (On-board debug unit) PX-ODB-AMT-20 (Trace unit)

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